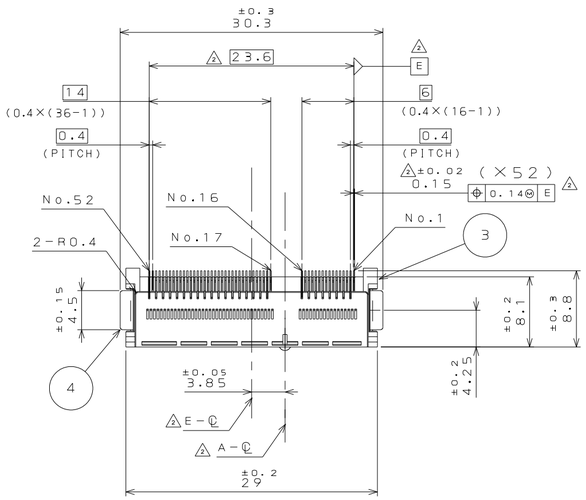
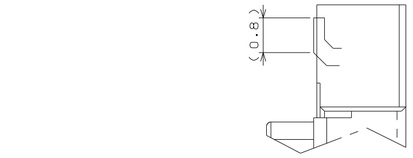
図面番号(DRAWING NO.) SJ111356

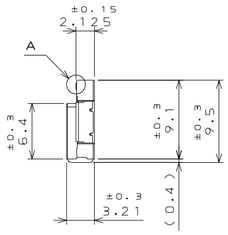
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	12.Sep.2011	000245	REVISED DIMENSION	———	H.KOIZUMI	R.KATOU	K.SHINDOU
3	6.Oct.2011	000272	ADD NOTE3	———	H.KOIZUMI	R.KATOU	K.SHINDOU

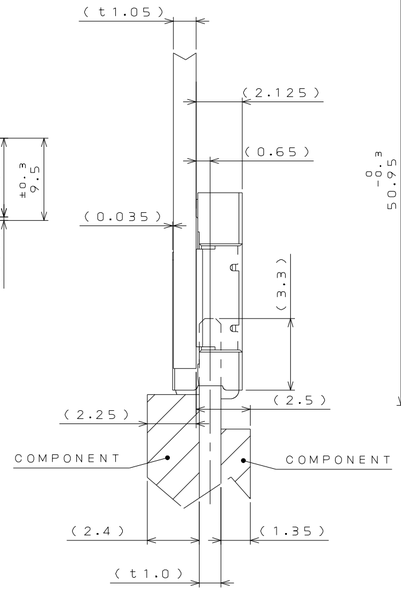
WISDOM承認 2011/10/18





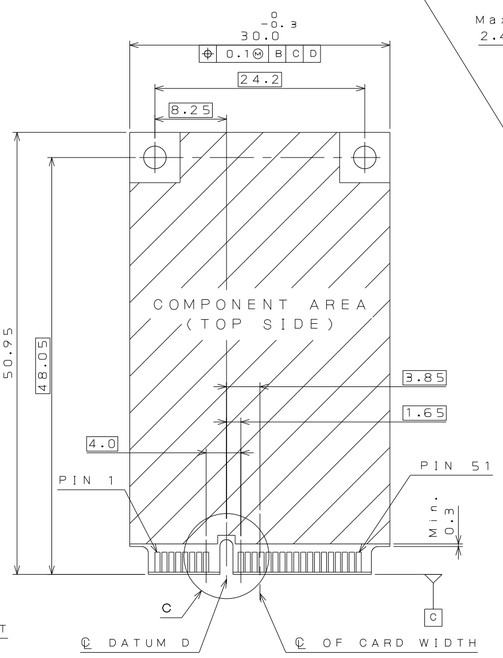
DETAIL A
(SCALE 10:1)





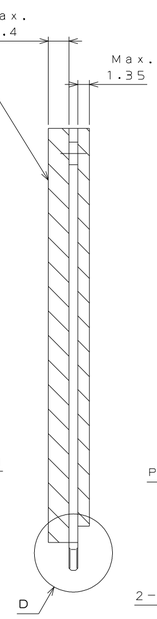
MOUNTING CONDITION(REF.)
実装状態図(参考)

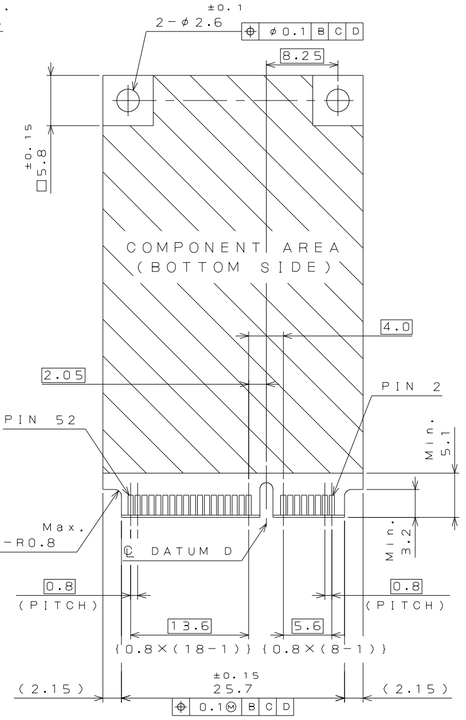
HATCHED AREAS ILLUSTRATE MAXMUM
AVAILABLE COMPONENT VOLUME.

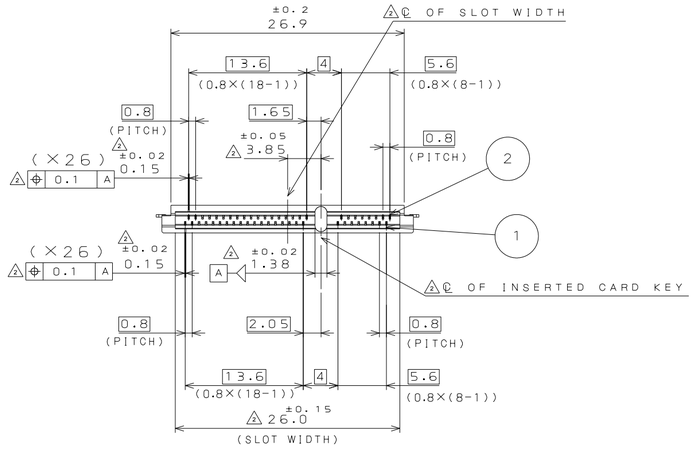


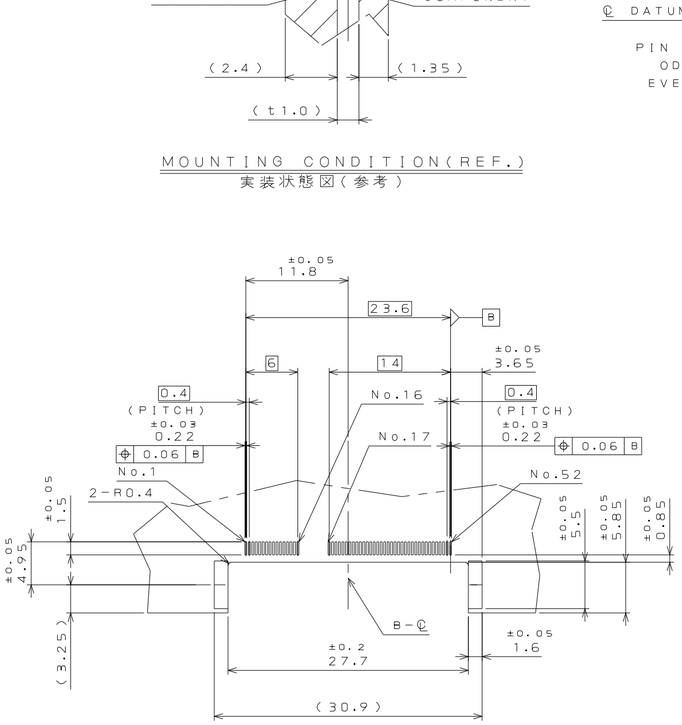
PIN NUMBERING REFERENCE :
ODD PINS - TOP SIDE
EVEN PINS - BOTTOM SIDE

APPLICABLE MINI CARD (REF.)

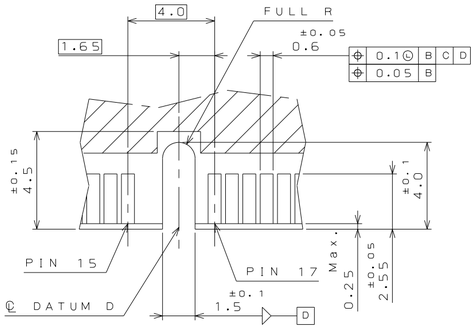




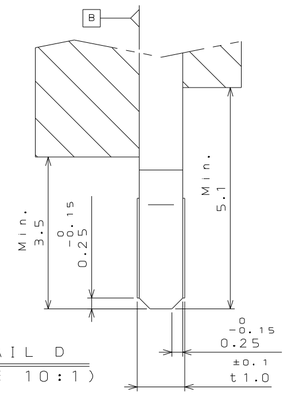




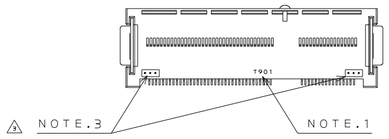
APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)



DETAIL C
(SCALE 5:1)



DETAIL D
(SCALE 10:1)



NOTE 1. PRODUCTION LOT No. AS INDICATED.

(Ex.) T901

- LOT NUMBER OF CURRENT MONTH
- MONTH (1 TO 9 FOR JAN. TO SEPT. RESPECTIVELY. OCT.:O. NOV.:X. DEC.:Y)
- YEAR (LAST DIGIT ONLY)
- MANUFACTURE CODE

NOTE 2. THE COPLANARITY OF CONTACT AND HOLD-DOWN BE 0.1 MAXIMUM.

NOTE 3. CAV NUMBER AND CORPORATE MARK AS INDICATED.

NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	HOLD DOWN	2	COPPER ALLOY	TIN PLATING	———
3	INSULATOR	1	THERMOPLASTIC	———	———
2	BOTTOM SIDE CONTACT	26	COPPER ALLOY	CONTACT AREA:Au(0.1μm MIN.) OVER Ni SOLDERING AREA:GOLD FLASH OVER Ni	———
1	TOP SIDE CONTACT	26	COPPER ALLOY	CONTACT AREA:Au(0.1μm MIN.) OVER Ni SOLDERING AREA:GOLD FLASH OVER Ni	———

仕様書(SPECIFICATION)		第1版(ORIGINAL DATE)	16.Feb.2011
		製図 DR.	———
一般公差(GENERAL TOLERANCE)		担当 CHK.	T.TSUJI
寸法(DIMENSION)	角度(ANGLES)	査閲 APPD.	———
. ±0.8	×° ±	承認 APPD.	K.IBARAKI
.× ±0.4	×°×' ±		
.×× ±0.1			
.××× ±			

尺度(SCALE)	5:1	シリーズ(SERIES)	MM60
名称(TITLE)	MM60-52C2-R1		
質量(MASS)			

日本航空電子工業株式会社
JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

図面番号(DRAWING NO.) SJ111356

SIZE A2

版数(REV.) 3

JAE CONNECTOR.COM
Reference Only

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DCF-G-213F(05.08)

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